



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16458Generic Copy

Issue Date: 22 Apr 2010**TITLE:** Qualification of NCP360, NCP361, NCP362 for Fabrication at ON Semiconductor Gresham Wafer Fab**PROPOSED FIRST SHIP DATE:** 22 Jul 2010**AFFECTED CHANGE CATEGORY(S):** ON Semi Fab Site**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or Shilpa Rao<shilpa.rao@onsemi.com>**SAMPLES:** Contact your local ON Semiconductor Sales Office**ADDITIONAL RELIABILITY DATA:** AvailableContact your local ON Semiconductor Sales Office or Edmond Gallard<edmond.gallard@onsemi.com>**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.**DESCRIPTION AND PURPOSE:**

ON Semiconductor is pleased to announce that the NCP360, NCP361, and NCP362 product families are now qualified for production at ON Semiconductor's Gresham wafer fab, located in Gresham, Oregon, USA.

Upon expiration or approval of the Final PCN, devices may be supplied from the Gresham wafer fab.

The Gresham wafer fab is compliant to ISO9001:2008, ISO/TS16949:2009, and ISO14001:2004. The devices have previously been manufactured at ON Semiconductor's Piestany, Slovakia wafer fab on the 0.8um PS5LV process. Devices are now qualified to run at Gresham on the 0.25um BCD process. Device performance is the same for the Gresham-sourced material as for the Piestany-sourced material. All devices continue to be assembled and tested in existing, qualified locations. No changes to packaging occur as a result of the wafer fab qualification.

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Products sourced from the Gresham wafer fab continue to meet ON Semiconductor's standards and requirements. Reliability test results for Gresham qualification material are summarized below.

Reliability Test Results:

Test	Conditions	Results
HTOL	Tj=+140C, 504 hours	Pass (0/80 x 5 lots)
HTSL	Ta=+150C, 1008 hours	Pass (0/80 x 1 lot – TSOP5 0/80 x 1 lot – UDFN)
LTSL	Ta=-40C, 168 hours	Pass (0/80 x 1 lot – TSOP5 0/80 x 2 lots – UDFN)
PC-TC	3 IR @ 260C; -65/+150C	Pass (0/80 x 1 lot – TSOP5 0/80 x 2 lots UDFN)
PC-UHAST	3 IR @ 260C; 121C, 15psi, 85%RH	Pass (0/80 x 1 lot UDFN)
ESD	2000V HBM 200V MM	Pass (2 lots) Pass (2 lots)
LU	Class II / 85C (+/- 100mA)	Pass (2 lots)
Electrical Distribution	-40C / +25C / +85C (Cpk>1.5)	Pass (2 lots)

ELECTRICAL CHARACTERISTIC SUMMARY:

There is no significant difference in electrical performance for the Gresham-sourced material. Characterization data is available upon request.

CHANGED PART IDENTIFICATION:

Products listed in the PCN with Finished Goods date codes representing WW 23, 2010 or later may be sourced from either Piastany or Gresham wafer fab die.



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List of affected General Parts:

NCP360MUTBG
NCP360SNAET1G
NCP360SNAET1GH
NCP360SNAFT1G
NCP360SNAFT1GH
NCP360SNAIT1G
NCP360SNT1G
NCP361MUTBG
NCP361SNT1G
NCP362AMUTBG
NCP362BMUTBG
NCP362CMUTBG